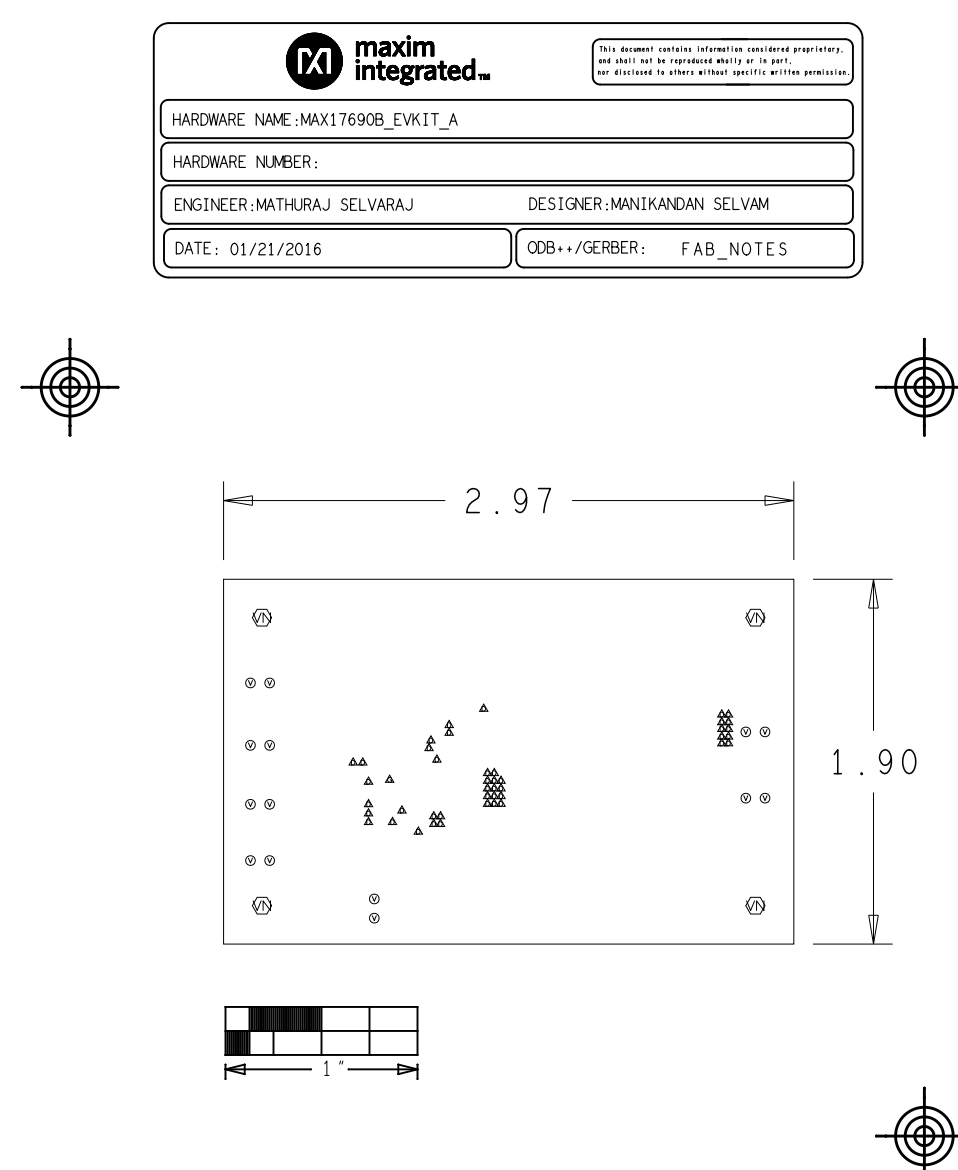
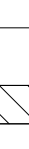







REV	DESCRIPTION	APPROVED	DATE
A	INITIAL RELEASE	ST	01/21/16

- NOTES: UNLESS OTHERWISE SPECIFIED
 1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
 MATERIAL: (USE CHECKED ITEMS FOR MATERIAL).
 2. BOARD MATERIAL:
 (X) FR4 (R0HS COMPLIANT) OR EQUIVALENT
 () ISOLA-FR408HR
 () NELCO-4000-13 OR EQUIVALENT
 () 370HR (R0HS COMPLIANT) OR EQUIVALENT
 () ROGERS 4350B
 () ROGERS 4003C
 () OTHER _____
 3. THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.
 WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
 4. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796
 WITH FLAMMABILITY RATING OF 94V-0
 5. OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES
 AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM
 TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
 6. BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.15%) PER LINEAR INCH.
 BOW & TWIST SHOULD BE MEASURED PER IPC-1M-650, METHOD 2-4.22.
 TOOLING: (USE CHECKED ITEMS FOR TOOLING)
 7. PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER R5274X OR ODB++ FORMAT FILE.
 DRILL LOCATION AND SIZE CONTROLLED BY EXCELLEN CMC DRILL FILE.
 8. IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY
 CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE
 SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC
 IMPEDANCE OF +/-0.10 OHS AS STATED IN THE LAMINATION DIAGRAM. THE
 VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND
 OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE
 WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.
 9. ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS
 WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
 () FILLETED
 (X) NOT FILLETED
 10. LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES.
 LEGEND TO LEGEND +/- 0.007 INCHES
 FINISH: (USE CHECKED ITEMS FOR PLATING)
 11. PLATING SPECIFICATION:
 () STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ), THE FINISH COPPER WEIGHT IS (1 OZ).
 FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT
 THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ)
 UNLESS OTHERWISE SPECIFIED
 () STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ), THE FINISH COPPER WEIGHT IS (2 OZ).
 FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT,
 THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).
 UNLESS OTHERWISE SPECIFIED
 (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ), THE FINISH COPPER WEIGHT IS (2 OZ) MINIMUM.
 FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT,
 THE STARTING WEIGHT CAN BE (1+2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ).
 UNLESS OTHERWISE SPECIFIED
 () OTHER _____
 12. CHECK ALL THAT APPLY
 () ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C
 (KNOOP HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C.
 GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0.
 CLASS 3 (50-100 MICRONS THICK) OVER ELECTRODEPOSITED NICKEL PLATE
 IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-400 MICRONS THICK).
 (X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER
 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 () FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER
 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 () FINGERS TO BE GOLD PLATED.
 () LEAD FREE AND R0HS COMPLIANT PLATING.
 () OTHER _____
 13. DRILL SIZES ARE FINISHED HOLE SIZES, ALL HOLES SHALL BE LOCATED WITHIN .005 DTP.
 MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR
 SO AS TO HINDER PROPER SOLDER WICKING.
 14. CHECK ALL THAT APPLY
 (X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI)
 PER ARTWORK.
 () GREEN TAIYO PSR-4000
 () OTHER _____
 15. CHECK ALL THAT APPLY
 (X) APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY
 BASED INK PER ARTWORK.
 () OTHER _____
 16. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYYY MM DD
 TESTING:
 17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.
 (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)
 THE PCB SHALL HAVE A VERIFICATION STAMP.
 18. A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE
 OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.
 MISCELLANEOUS:
 19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN
 USED AS VIA-IN PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED
 WITH NON-CONDUCTIVE EPOXY, UNLESS OTHERWISE SPECIFIED.
 20. FOR ALL DRILL INFORMATION REFER TO DRILL CHART:
 () NON-CONDUCTIVE EPOXY, FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
 () SILVER, FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
 21. FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITTS, SCRATCHES PROBE MARKS
 OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT
 SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE, NOT TO EXCEED +/- .0001" OF FLATNESS.
 22. THIEVING:
 () SUPPLIER MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 (X) SUPPLIER MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 23. PENMUT
 () PENMUTS TO BE INSTALLED BY SUPPLIER.
 () PENMUTS NOT TO BE INSTALLED BY SUPPLIER.
 (X) NOT APPLICABLE
 24. GND_SIGNAL AND GND_POWER NETS ARE INTENTIONALLY SHORTED ON L2_GND LAYER.



LAMINATION DIAGRAM					
LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (OZ)	DIELECTRIC THICKNESS (in.)	DIELECTRIC MATERIAL	
1	TOP	2		FOIL	
2	L2_GND	1		TBD	FR4 (RoHS)/EQUIV
3	L3_PWR	1		TBD	FR4 (RoHS)/EQUIV
4	BOTTOM	2		TBD	FR4 (RoHS)/EQUIV
				FOIL	
THE FINISHED PCB THICKNESS TO BE:			0.0625" +/- 0.010"		

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
	12.0	+3.0/-10.0	PLATED	43
	20.0	+3.0/-18.0	PLATED	1
	39.37	+3.0/-3.0	PLATED	14
	125.0	+3.0/-3.0	PLATED	4

TOLERANCES UNLESS OTHERWISE SPECIFIED		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		 maxim integrated™	
FRACTIONS DECIMALS ANGLES $\frac{.}{.}/\frac{.}{.}$.XX $\frac{.}{.}$.01 .XXX $\frac{.}{.}$.005 $\frac{.}{.}/\frac{.}{.}$				HARDWARE NAME : MAX17690B_EVKIT_A	
MATERIAL:		DRAWN BY: MANIKANDAN S DATE: 01/21/16			
SEE NOTES		CHECKED BY: SAIKUMAR T DATE: 01/21/16		REV A	
FINISH:		APPR. BY: SAIKUMAR T DATE: 01/21/16		HARDWARE NUMBER:	
SEE NOTES		APPR. BY: DATE:		XX-XXXX-XXX NOT TO SCALE TEMPLATE REV: 2.1 SHEET 1 OF 1	